

Form PTO-1449 (modified) List of Patents and Publications For Applicant's Information Disclosure Statement (Use several sheets if necessary)				ATTY. DOCKET NO. MCRO:199--3/FLE (95-0057.03)		SERIAL NO. 09/901,837 Unassigned	
				APPLICANT Shubneesh Batra et al.			
				FILING DATE Herewith		GROUP Unassigned 2825	

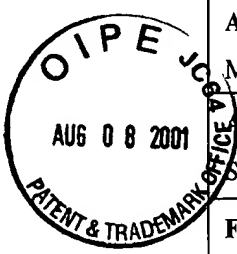
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U.S. PATENT DOCUMENTS							
EXAM. INIT.	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
CME	A1	4,742,014	05/03/88	Hooper et al.	437	192	05/10/85
CME	A2	4,758,533	07/19/88	Magee et al.	437	173	09/22/87
CME	A3	4,811,067	03/07/89	Fitzgerald et al.	357	23.6	05/02/86
CME	A4	4,970,176	11/13/90	Tracy et al.	437	187	09/29/89
CME	A5	4,985,750	01/15/91	Hoshino	357	71	09/17/87
CME	A6	5,019,533	05/28/91	Cuddihy et al.	437	199	05/26/89
CME	A7	5,169,803	12/08/92	Miyakawa	437	197	11/27/91
CME	A8	5,266,521	11/30/93	Lee et al.	437	188	01/31/92
CME	A9	5,293,053	03/08/94	Malhi et al.	257	330	05/01/91
CME	A10	5,312,774	05/17/94	Nakamura et al.	437	192	12/03/92
CME	A11	5,324,973	06/28/94	Sivan	257	330	05/03/93
CME	A12	5,350,712	09/27/94	Shibata	437	195	09/16/93
CME	A13	5,358,616	10/25/94	Ward	204	192.15	02/17/93
CME	A14	5,360,524	11/01/94	Hendel et al.	204	192.25	04/13/93
CME	A15	5,534,463	07/09/96	Lee et al.	437	195	01/25/93
CME	A16	5,567,243	10/22/96	Foster et al.	118	730	06/06/95
CME	A17	5,571,749	11/05/96	Matsuda et al.	437	113	12/28/94
CME	A18	5,691,571	11/25/97	Hirose et al.	257	751	12/26/95
CME	A19	5,751,064	05/12/98	Bryant et al.	257	752	03/03/95
CME	A20	5,831,335	11/03/98	Miyamoto	257	757	01/24/96
CME	A21	5,846,877	12/08/98	Kim	438	625	12/08/95
CME	A22	5,856,706	01/05/99	Lee	257	758	11/13/95
CME	A23	5,869,902	02/09/99	Lee et al.	257	773	03/11/96
CME	A24	5,880,023	03/09/99	Jun	438	652	01/05/96

FOREIGN PATENT DOCUMENTS							
EXAM. INT.	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSPATENTATION
OTHER ART (Author, Title, Journal, Volume, Pertinent Pages, & Date)							
<i>CME</i>	B1	K. Kikuta, et al., "Al-Ge Reflow Sputtering for Submicron-Contact-Hole Filling," 1991, Proc. 8 th International IEEE VLSI Multilevel Interconnection Conf., pgs. 163-169.					
<i>CME</i>	B2	K. Hirose et al., "Surface Melting Model for Al Reflow into Submicron Contact-holes and Vias," 1994, IEEE, pgs. 557-560.					
<i>CME</i>	B3	K. Kikuta et al., "Aluminum-Germanium-Copper Multilevel Damascene Process using Low Temperature Reflow Sputtering and Chemical Mechanical Polishing," 1994, IEEE, pgs. 101-104.					
<i>CME</i>	B4	I.S. Park et al., "A Novel Al-Reflow Process Using Surface Modification by the ECR Plasma Treatment and Its Application to the 256Mbit DRAM," 1994, IEEE, pgs. 109-112.					
EXAMINER <i>C. Luchant</i>				DATE CONSIDERED <i>8-17-02</i>			
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Information Disclosure Statement--PTO-1449 (Modified)

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		APPLICANT Shubneesh Batra et al.	
		FILING DATE July 10, 2001	GROUP 2825 Unassigned

U.S. PATENT DOCUMENTS

EXAM. INIT.	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
CME	A1	5,719,446	02/17/98	Taguchi et al.	257	751	02/12/97
CME	A2	5,897,370	04/27/99	Joshi et al.	438	632	10/28/96

FOREIGN PATENT DOCUMENTS

EXAM. INIT.	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION

OTHER ART (Author, Title, Journal, Volume, Pertinent Pages, & Date)

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EXAMINER <i>C. Juresk</i>	DATE CONSIDERED 8-17-02
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